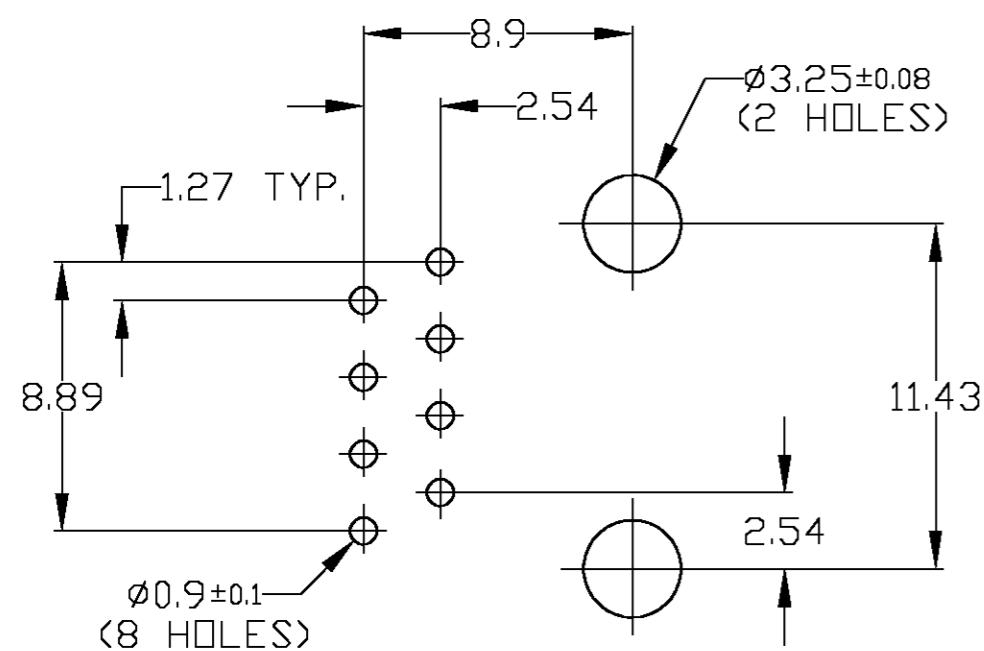
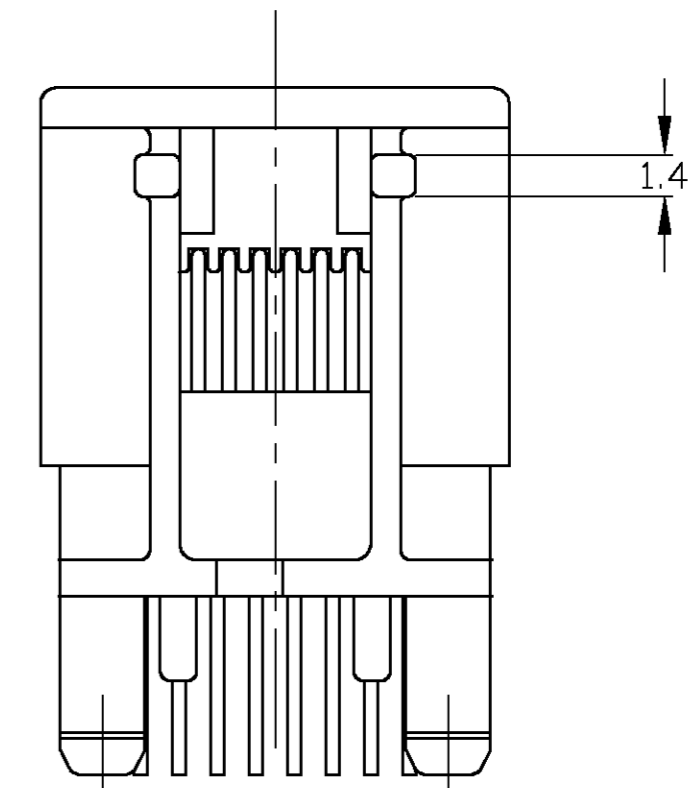
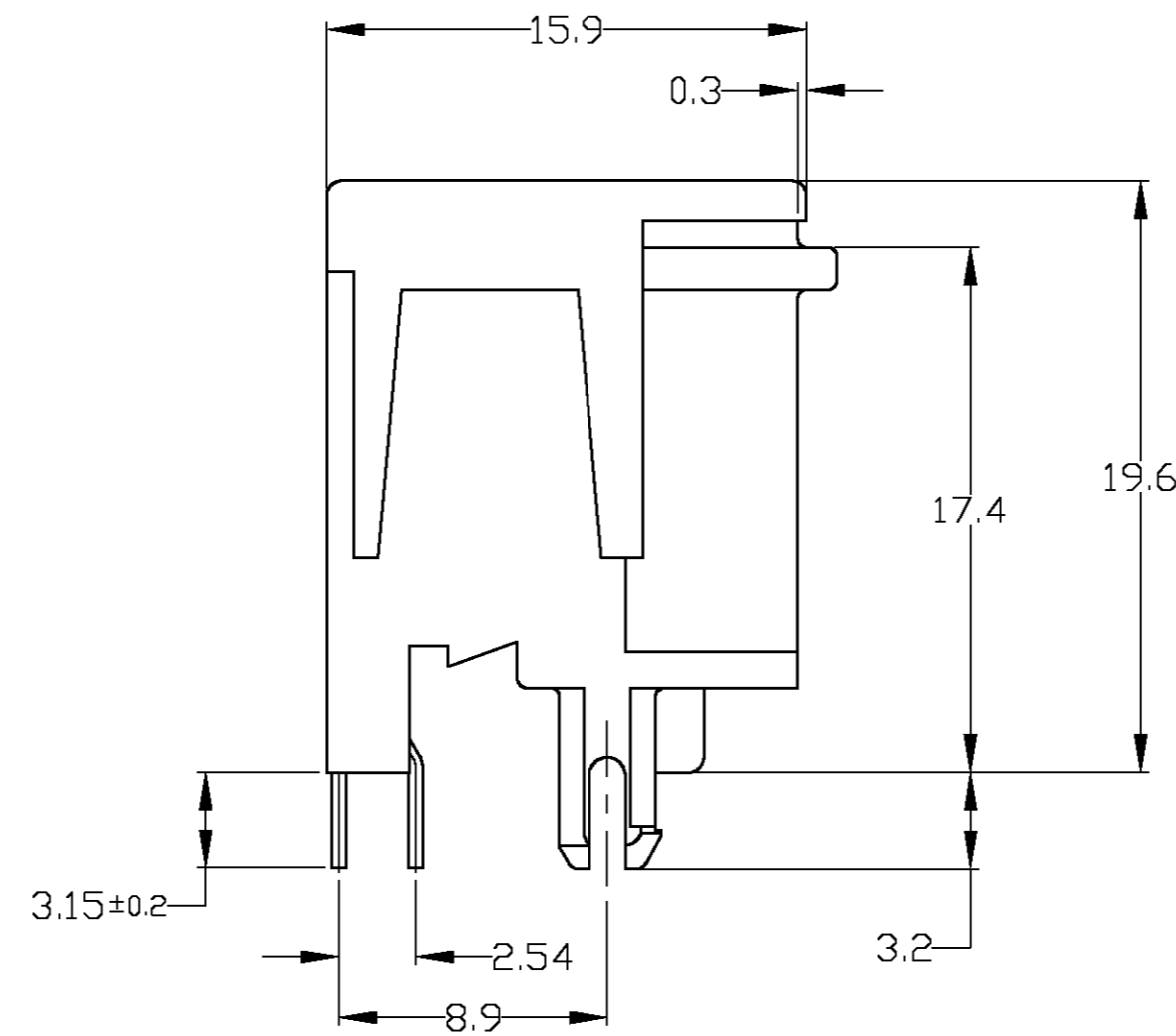
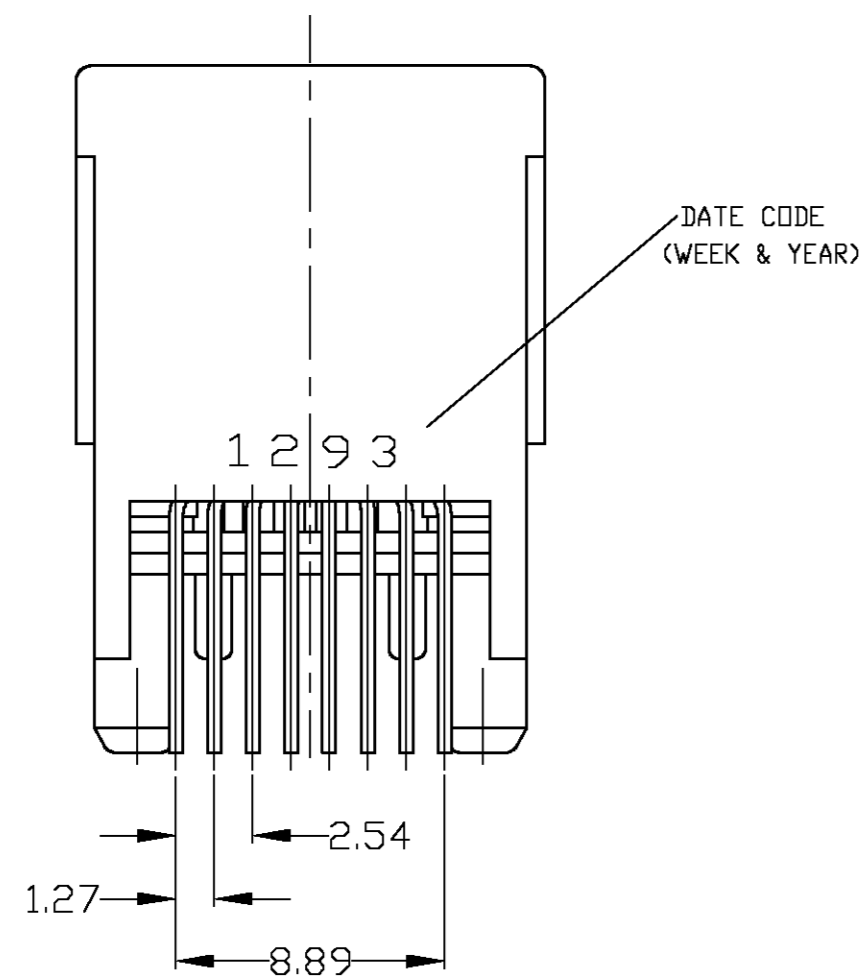


NOTES:

- 1 TOLERANCES UNLESS OTHERWISE SPECIFIED: $\pm 0,15$.
- 2 CONTACTS;
1,27 μ m MIN. GOLD, SELECTIVE IN CONTACT AREA, OVER 1,27 μ m MIN. NICKEL.
2,0 μ m MIN. TIN-LEAD OVER 1,27 μ m MIN. NICKEL ON SOLDER TINES.
- 3 HOUSING;
PBT, COLOR BLACK, UL 94V-0
CONTACTS;
PHOSPHOR BRONZE.
- 4 FOR APPLICATION INFORMATION SEE AMP SPEC. 114-19019.
- 5 FOR PERFORMANCE REQUIREMENTS SEE AMP SPEC. 108-19064.
- 6 PACKAGING: BULK PACKAGED.
TRUE POSITIONING OF THE SOLDER TINES,
MAY BE AFFECTED BY BULK PACKAGING.

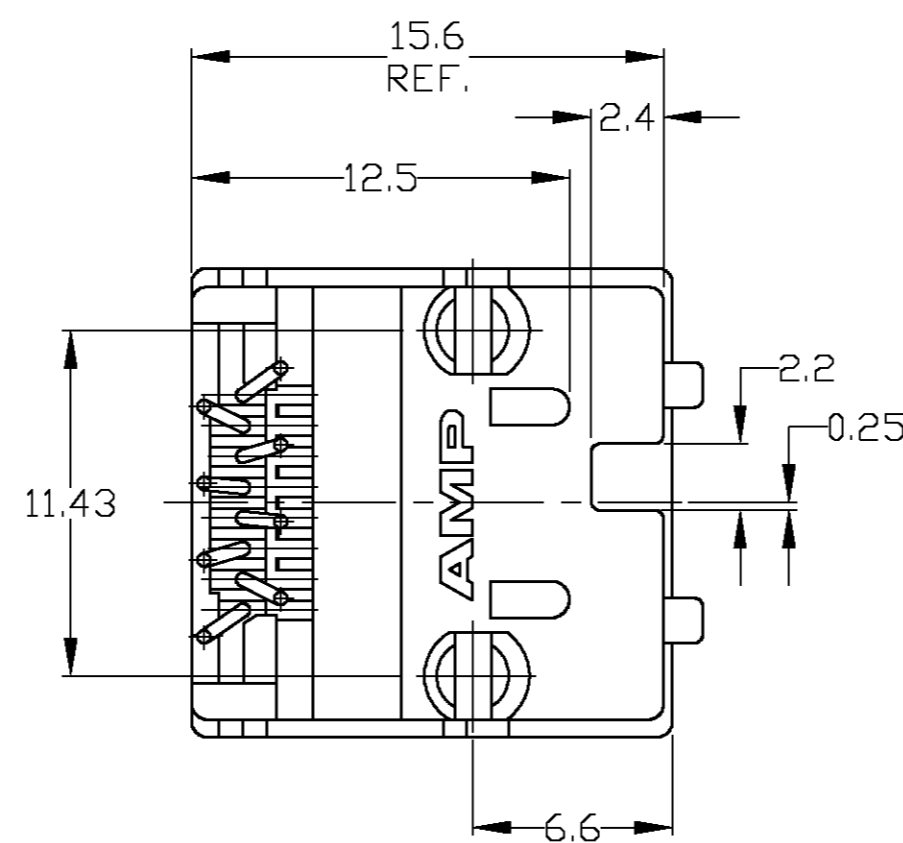


PRINTED CIRCUIT BOARD LAYOUT

[VIEW SHOWN IS CIRCUIT (NONCOMPONENT) SIDE OF BOARD.]

PRINTED CIRCUIT BOARD THICKNESS: 1,6 mm NOMINAL.

TOLERANCES UNLESS OTHERWISE SPECIFIED: $\pm 0,05$.



8 POS. / 8 CONT.				338360-1	
DESCRIPTION	FINISH	MATERIAL		P/N	
		CUSTOMER DRAWING		FOR REFERENCE ONLY WILL NOT BE UPDATED	
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		THIS DRAWING IS UNPUBLISHED			
		RELEASED FOR PUBLICATION			
B	SR10-00B4-02	KV	06 FEB 02	Tyco Electronics Corporation Oostkamp - BELGIUM	
A	EH-1142-97	EVE	W.B. 18 NOV 97		
O	EH-0870-97	EVE	W.B. 12 AUG 97		
LTR.	REVISION RECORD	DR.	CHK.	DATE	NAME MODULAR JACK, 8 POS., TOP ENTRY HIGH PROFILE, WITH SPECIAL PANEL STOPS FOR PRINTED CIRCUIT BOARD
DR.: E.v.EJK	CHK.: W.BRUMMANS	APP.: R.SMEETS	DWG.No.	REV.LTR.	SHEET
DATE: 12 AUG 97	DATE:	DATE:	C-338360	B	1 OF 1